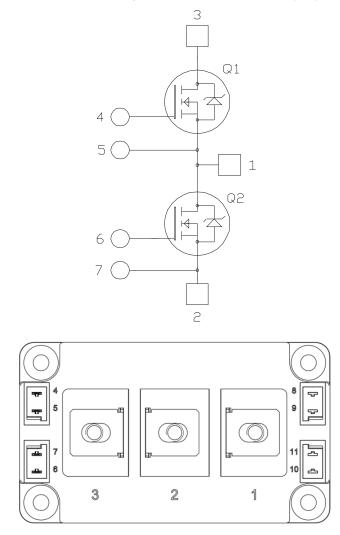


# Phase Leg SiC Power Module

#### **Product Overview**

The MSCSM120AM042D3AG device is a phase leg 1200V, 495A silicon carbide (SiC) MOSFET power module.



Note: All ratings at  $T_J$  = 25 °C, unless otherwise specified.

Δ CAUTION These devices are sensitive to electrostatic discharge. Proper handling procedures must be followed.

#### Features

The following are key features of the MSCSM120AM042D3AG device:

- SiC Power MOSFET
  - Low R<sub>DS(on)</sub>
  - High temperature performance
- Kelvin emitter for easy drive
- High level of integration
- M6 power connectors
- Aluminum Nitride (AIN) substrate for improved thermal performance

#### Benefits

The following are the benefits of MSCSM120AM042D3AG device:

- High efficiency converter
- Stable temperature behavior
- Direct mounting to heatsink (isolated package)
- Low junction-to-case thermal resistance
- RoHS compliant

#### Application

The MSCSM120AM042D3AG device is designed for the following applications:

- Welding converters
- Switched mode power supplies
- Uninterruptible power supplies
- EV motor and traction drive

#### 1. Electrical Specifications

This section provides the electrical specifications of the MSCSM120AM042D3AG device.

#### 1.1 SiC MOSFET Characteristics (Per SiC MOSFET)

The following table lists the absolute maximum ratings per SiC MOSFET of the MSCSM120AM042D3AG device.

#### Table 1-1. Absolute Maximum Ratings

Symbol	Parameter		Maximum Ratings	Unit
V <sub>DSS</sub>	Drain-Source voltage		1200	V
I <sub>D</sub>	Continuous drain current	T <sub>C</sub> = 25 °C	495 <sup>1</sup>	A
		T <sub>C</sub> = 80 °C	395 <sup>1</sup>	
I <sub>DM</sub>	Pulsed drain current		990	
V <sub>GS</sub>	Gate-Source voltage		-10/23	V
R <sub>DS(on)</sub>	Drain-Source ON resistance		5.2	mΩ
P <sub>D</sub>	Power dissipation	T <sub>C</sub> = 25 °C	2031	W

#### Note:

1. SiC MOSFET device specification, but the output current must be limited due to the size of the power connectors.

The following table lists the electrical characteristics per SiC MOSFET of the MSCSM120AM042D3AG device.

Table 1-2. Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min.	Тур.	Max.	Unit
I <sub>DSS</sub>	Zero gate voltage drain current	V <sub>GS</sub> = 0V V <sub>DS</sub> = 1200V		—	60	600	μA
R <sub>DS(on)</sub>	Drain-Source on	V <sub>GS</sub> = 20V	T <sub>J</sub> = 25 °C		4.2	5.2	mΩ
	resistance	I <sub>D</sub> = 240A	T <sub>J</sub> = 175 °C		6.7	_	
V <sub>GS(th)</sub>	Gate threshold voltage	$V_{GS} = V_{DS}$ I <sub>D</sub> = 18 mA		1.8	2.8	—	V
I <sub>GSS</sub>	Gate–Source leakage current	$V_{GS}$ = 20V; $V_{DS}$ = 0V		_	_	600	nA

**Electrical Specifications** 

The following table lists the dynamic characteristics per SiC MOSFET of the MSCSM120AM042D3AG device.

Symbol	Characteristic	Test Conditions		Min.	Тур.	Max.	Unit
C <sub>iss</sub>	Input capacitance	V <sub>GS</sub> = 0V		-	18.1	—	nF
C <sub>oss</sub>	Output capacitance	V <sub>DS</sub> = 1000V		—	1.6	—	
C <sub>rss</sub>	Reverse transfer capacitance	f = 1 MHz		_	0.15		
Qg	Total gate charge	V <sub>GS</sub> = -5V/20V		-	1392	—	nC
Q <sub>gs</sub>	Gate-Source charge	V <sub>Bus</sub> = 800V		_	246	—	
Q <sub>gd</sub>	Gate-Drain charge	I <sub>D</sub> = 240A		_	300	—	
T <sub>d(on)</sub>	Turn-on delay time	V <sub>GS</sub> = -5V/20V	T <sub>J</sub> = 150 °C	_	66	_	ns
Tr	Rise time	V <sub>Bus</sub> = 600V		—	74	—	
T <sub>d(off)</sub>	Turn-off delay time	I <sub>D</sub> = 300A		_	166	_	
T <sub>f</sub>	Fall time	R <sub>GON</sub> = 4.7Ω R <sub>GOFF</sub> = 1.8Ω		—	67	_	
Eon	Turn-on energy	V <sub>GS</sub> = -5V/20V	T <sub>J</sub> = 150 °C	_	9.5	_	mJ
E <sub>off</sub>	Turn-off energy	V <sub>Bus</sub> = 600V I <sub>D</sub> = 300A R <sub>GON</sub> = 4.7Ω R <sub>GOFF</sub> = 1.8Ω		_	4.3	—	
R <sub>Gint</sub>	Internal gate resistance	e		-	1	_	Ω
R <sub>thJC</sub>	Junction-to-case therm	nal resistance		_	_	0.074	°C/W

#### Table 1-3. Dynamic Characteristics

The following table lists the body diode ratings and characteristics per SiC MOSFET of the MSCSM120AM042D3AG device.

Table 1-4. Body Diode Ratings and Characteristics

Symbol	Characteristic	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>SD</sub>	Diode forward voltage	$V_{GS}$ = 0V; I <sub>SD</sub> = 240A		4		V
		$V_{GS} = -5V; I_{SD} = 240A$	—	4.2		
t <sub>rr</sub>	Reverse recovery time	$I_{SD}$ = 240A; $V_{GS}$ = -5V		90		ns
Q <sub>rr</sub>	Reverse recovery charge	$V_{R}$ = 800V; di <sub>F</sub> /dt = 6000 A/µs		3300		nC
Irr	Reverse recovery current			81		А

#### **Electrical Specifications**

#### 1.2 Thermal and Package Characteristics

The following table lists the thermal and package characteristics of the MSCSM120AM042D3AG device.

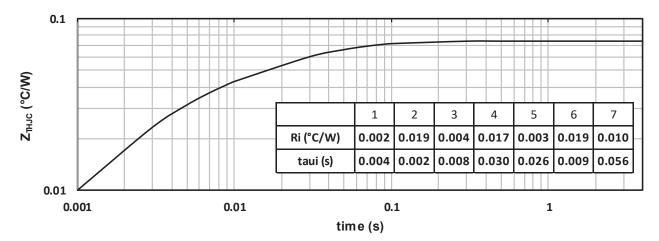
Symbol	Characteristics	Characteristics		Min.	Max.	Unit
V <sub>ISOL</sub>	RMS isolation voltage, any termin	al to case t =1 min,	50 Hz/60 Hz	4000	—	V
TJ	Operating junction temperature ra	inge		-40	175	°C
T <sub>JOP</sub>	Recommended junction temperat	ure under switching	conditions	-40	T <sub>Jmax</sub> –25	
T <sub>STG</sub>	Storage temperature range			-40	125	
T <sub>C</sub>	Operating case temperature			-40	125	
Torque	Mounting torque	For terminals	M6	3	5	N.m
		To heatsink	M6	3	5	
Wt	Package weight			_	350	g

#### Table 1-5. Thermal and Package Characteristics

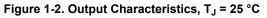
**Electrical Specifications** 

#### 1.3 Typical SiC MOSFET Performance Curve

This section shows the typical SiC MOSFET performance curves of the MSCSM120AM042D3AG device.







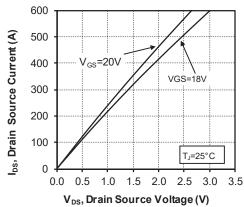


Figure 1-4. Normalized R<sub>DS(on)</sub> vs. Temperature

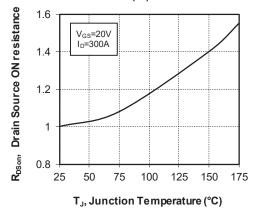


Figure 1-3. Output Characteristics, T<sub>J</sub> = 175 °C

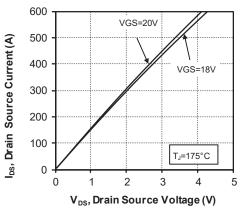
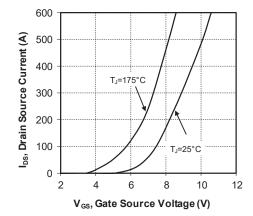
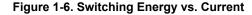
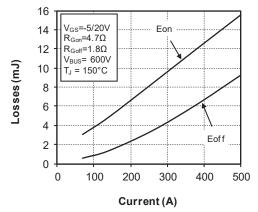


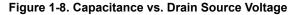
Figure 1-5. Transfer Characteristics

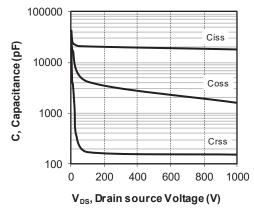


**Electrical Specifications** 











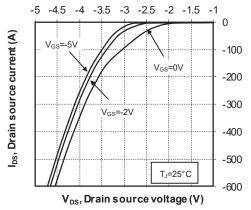


Figure 1-7. Switching Energy vs. Rg

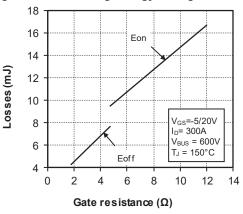


Figure 1-9. Gate Charge vs. Gate Source Voltage

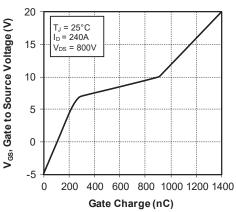
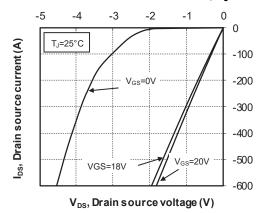
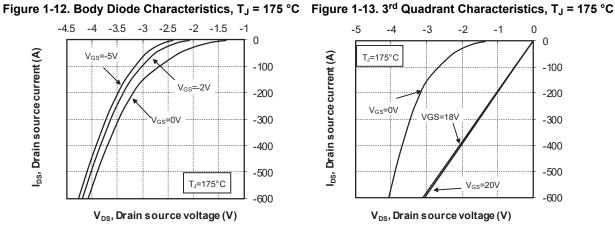


Figure 1-11. 3<sup>rd</sup> Quadrant Characteristics, T<sub>J</sub> = 25 °C



**Electrical Specifications** 



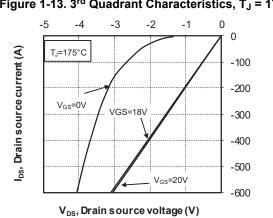
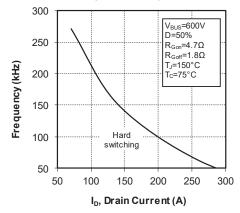


Figure 1-14. Operating Frequency vs Drain Current



#### Package Specifications

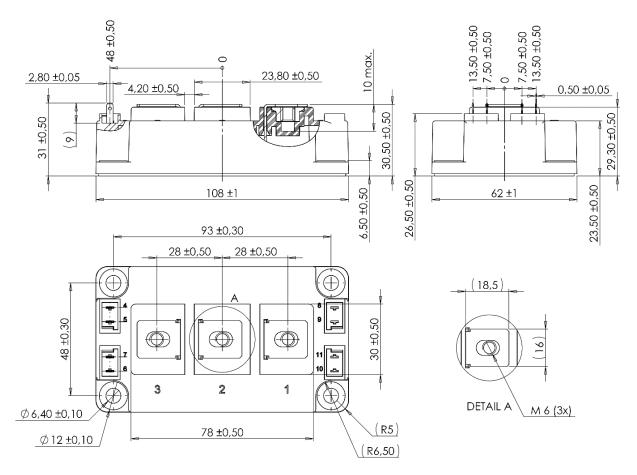
#### 2. Package Specifications

The following section shows the package specification of the MSCSM120AM042D3AG device.

#### 2.1 Package Outline

The following figure shows the package outline drawing of the MSCSM120AM042D3AG device. The dimensions in the following figure are in millimeters.

#### Figure 2-1. Package Outline Drawing



Note: See 1908—Mounting Instructions for D3 and D4 Power Modules for more information.

# 3. Revision History

Revision	Date	Description
Α	06/2022	Initial Revision

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